

separating the first receiving substrate and the first portion of the semiconductor devices from the substrate;  
 coupling a second receiving substrate with a second portion of the semiconductor devices; and  
 separating the second receiving substrate and the second portion of the semiconductor devices from the substrate.

**10.** The method of claim **8**, wherein coupling the at least one receiving substrate with the semiconductor devices comprises coupling at least one flexible receiving substrate with the semiconductor devices.

**11.** The method of claim **1**, wherein separating the semiconductor devices from the substrate comprises separating the semiconductor devices from the protuberances which remain coupled with the substrate.

**12.** The method of claim **1**, wherein separating the semiconductor devices from the substrate comprises separating the semiconductor devices having the protuberances coupled therewith from the substrate.

**13.** The method of claim **12**, wherein etching the protuberances comprises etching the protuberances into shapes of lenses operable to focus light on the corresponding semiconductor devices.

**14.** The method of claim **1**, further comprising, after separating the semiconductor devices from the substrate:  
 removing the protuberances from the substrate; and  
 forming a layer over the substrate after the removal of the protuberances from the substrate.

**15.** An apparatus comprising:

a substrate;

a plurality of semiconductor devices over the substrate, wherein the semiconductor devices are substantially released from the substrate; and

a protuberance between each of the substantially released semiconductor devices and the substrate.

**16.** The apparatus of claim **15**, wherein the protuberance has a graded composition.

**17.** The apparatus of claim **15**, wherein the semiconductor devices comprise photovoltaic devices, and wherein the protuberance comprises a group III-V compound semiconductor material.

**18.** The apparatus of claim **15**, further comprising at least one anchor that is coupled between a semiconductor device of the plurality and an adjacent fixed structure.

**19.** A method comprising:

coupling a first receiving substrate with a first subset of semiconductor devices, each of the semiconductor devices of the first subset disposed over a substrate with a corresponding protuberance disposed between the semiconductor device of the first subset and the substrate;

separating the first receiving substrate and the first subset of the semiconductor devices from the substrate;

coupling a second receiving substrate with a second subset of the semiconductor devices, each of the semiconductor devices of the second subset disposed over the substrate with a corresponding protuberance disposed between the semiconductor device of the second subset and the substrate; and

separating the second receiving substrate and the second subset of the semiconductor devices from the substrate.

**20.** The method of claim **19**, wherein the protuberances have graded compositions.

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